Renesas Electronics America Inc - UPD78F0534AGC-GAL-AX Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	78K/0
Core Size	8-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I²C, LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	55
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f0534agc-gal-ax

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CHAPTER 1 OUTLINE

1.1 Differences Between Conventional-specification Products (μPD78F05xx and 78F05xxD) and Expanded-specification Products (μPD78F05xxA and 78F05xxDA)

The differences between the conventional-specification products (μPD78F05xx and 78F05xxD) and expanded-specification products (μPD78F05xxA and 78F05xxDA) of the 78K0/Kx2 microcontrollers are described below.

- A/D conversion time
- X1 oscillator characteristics
- Instruction cycle, peripheral hardware clock frequency, external main system clock frequency, external main system clock input high-level width, and external main system clock input low-level width (AC characteristics)
- The number of flash memory rewrites and retention time
- Processing time of the self programming library
- Interrupt response time of the self programming library

(d) Auxiliary carry flag (AC)

If the operation result has a carry from bit 3 or a borrow at bit 3, this flag is set (1). It is reset (0) in all other cases.

(e) In-service priority flag (ISP)

This flag manages the priority of acknowledgeable maskable vectored interrupts. When this flag is 0, low-level vectored interrupt requests specified by a priority specification flag register (PR0L, PR0H, PR1L, PR1H) (see **20.3 (3) Priority specification flag registers (PR0L, PR0H, PR1L, PR1H)**) can not be acknowledged. Actual request acknowledgment is controlled by the interrupt enable flag (IE).

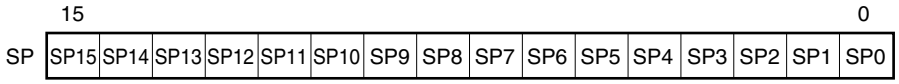
(f) Carry flag (CY)

This flag stores overflow and underflow upon add/subtract instruction execution. It stores the shift-out value upon rotate instruction execution and functions as a bit accumulator during bit operation instruction execution.

(3) Stack pointer (SP)

This is a 16-bit register to hold the start address of the memory stack area. Only the internal high-speed RAM area can be set as the stack area.

Figure 3-22. Format of Stack Pointer



The SP is decremented ahead of write (save) to the stack memory and is incremented after read (restored) from the stack memory.

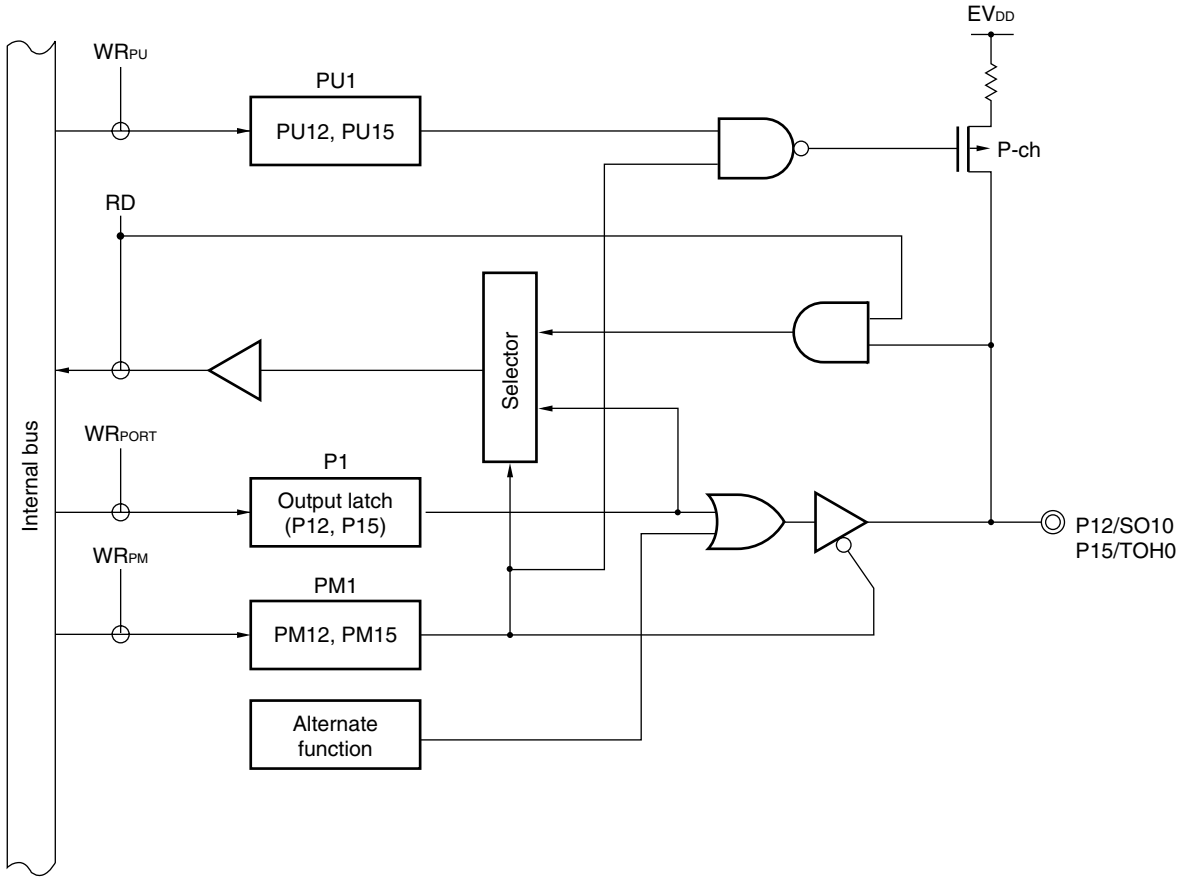
Each stack operation saves/restores data as shown in Figures 3-23 and 3-24.

Caution Since reset signal generation makes the SP contents undefined, be sure to initialize the SP before using the stack.

Remark Note the following points to use the memory bank select function efficiently.

- Allocate a routine that is used often in the common area.
- If a value that is planned to be referenced is placed in RAM, it can be referenced from all of the areas.
- If the reference destination and the branch destination of the routine placed in a memory bank are placed in the same memory bank, then the code size and processing are more efficient.
- Allocate interrupt servicing that requires a quick response in the common area.

Figure 5-9. Block Diagram of P12 and P15



P1: Port register 1
PU1: Pull-up resistor option register 1
PM1: Port mode register 1
RD: Read signal
WR××: Write signal

Remark With products not provided with an EVDD or EVSS pin, replace EVDD with VDD, or replace EVSS with VSS.

5.2.4 Port 3

	78K0/KB2	78K0/KC2	78K0/KD2	78K0/KE2		78K0/KF2
				Products whose flash memory is less than 32 KB	Products whose flash memory is at least 48 KB	
P30/INTP1	√					
P31/INTP2/OCD1A[Note]	√					
P32/INTP3/OCD1B[Note]	√					
P33/INTP4/TI51/TO51	√					

Note OCD1A and OCD1B are provided to the products with an on-chip debug function (μPD78F05xxD and 78F05xxDA) only.

Remark √: Mounted

Port 3 is an I/O port with an output latch. Port 3 can be set to the input mode or output mode in 1-bit units using port mode register 3 (PM3). When the P30 to P33 pins are used as an input port, use of an on-chip pull-up resistor can be specified in 1-bit units by pull-up resistor option register 3 (PU3).

This port can also be used for external interrupt request input and timer I/O.

Reset signal generation sets port 3 to input mode.

Figures 5-13 and 5-14 show block diagrams of port 3.

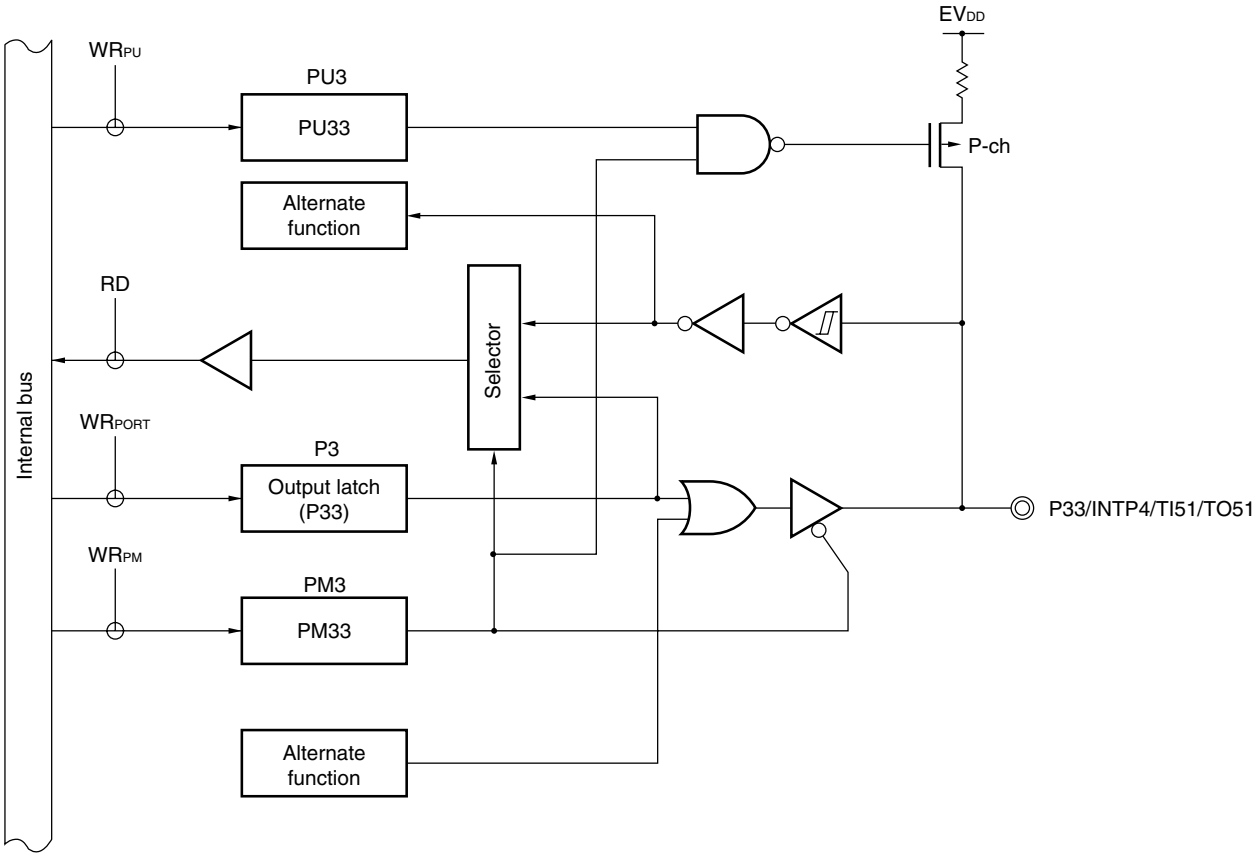
Cautions 1. In the product with an on-chip debug function (μP78F05xxD and D78F05xxDA), be sure to pull the P31/INTP2/OCD1A pin down before a reset release, to prevent malfunction.

2. Process the P31/INTP2/OCD1A pin of the products mounted with the on-chip debug function (μPD78F05xxD and 78F05xxDA) as follows, when it is not used when it is connected to a flash memory programmer or an on-chip debug emulator.

		P31/INTP2/OCD1A
Flash memory programmer connection		Connect to EV_{SS}[Note] via a resistor.
On-chip debug emulator connection (when it is not used as an on-chip debug mode setting pin)	During reset	
	During reset released	Input: Connect to EV_{DD}[Note] or EV_{SS}[Note] via a resistor. Output: Leave open.

Note With products without an EV_{SS} pin, connect them to V_{SS}. With products without an EV_{DD} pin, connect them to V_{DD}.

Figure 5-14. Block Diagram of P33



P3: Port register 3
PU3: Pull-up resistor option register 3
PM3: Port mode register 3
RD: Read signal
WR××: Write signal

Remark With products not provided with an EV_{DD} or EV_{SS} pin, replace EV_{DD} with V_{DD}, or replace EV_{SS} with V_{SS}.

7.4.3 External event counter operation

When bits 1 and 0 (PRM0n1 and PRM0n0) of the prescaler mode register 0n (PRM0n) are set to 11 (for counting up with the valid edge of the TI00n pin) and bits 3 and 2 (TMC0n3 and TMC0n2) of 16-bit timer mode control register 0n (TMC0n) are set to 11, the valid edge of an external event input is counted, and a match interrupt signal indicating matching between TM0n and CR00n (INTTM00n) is generated.

To input the external event, the TI00n pin is used. Therefore, the timer/event counter cannot be used as an external event counter in the clear & start mode entered by the TI00n pin valid edge input (when TMC0n3 and TMC0n2 = 10).

The INTTM00n signal is generated with the following timing.

- Timing of generation of INTTM00n signal (second time or later)
  = Number of times of detection of valid edge of external event × (Set value of CR00n + 1)

However, the first match interrupt immediately after the timer/event counter has started operating is generated with the following timing.

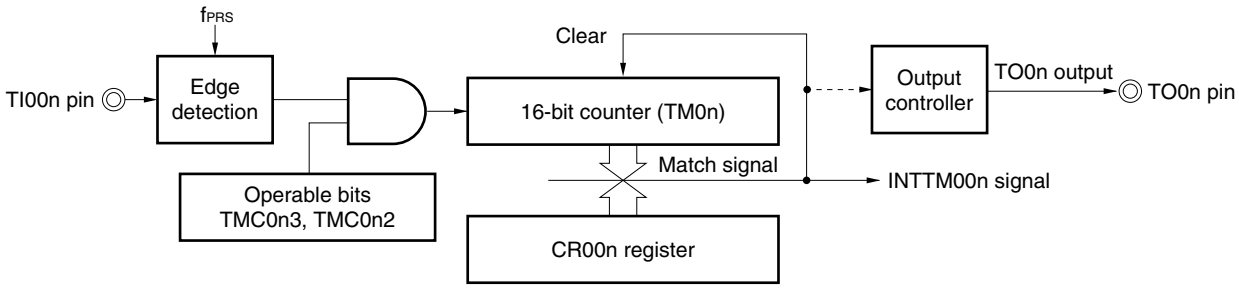
- Timing of generation of INTTM00n signal (first time only)
  = Number of times of detection of valid edge of external event input × (Set value of CR00n + 2)

To detect the valid edge, the signal input to the TI00n pin is sampled during the clock cycle of f_{PRS}. The valid edge is not detected until it is detected two times in a row. Therefore, a noise with a short pulse width can be eliminated.

Remarks 1. For the setting of I/O pins, see **7.3 (5) Port mode register 0 (PM0)**.

2. For how to enable the INTTM00n signal interrupt, see **CHAPTER 20 INTERRUPT FUNCTIONS**.

Figure 7-24. Block Diagram of External Event Counter Operation

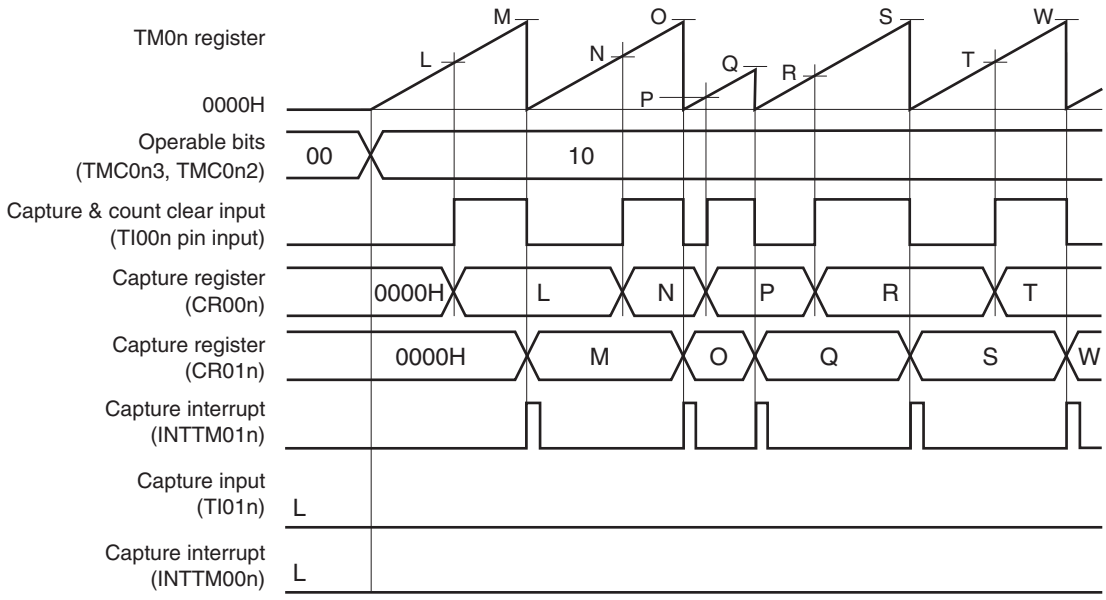


Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products

n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

Figure 7-34. Timing Example of Clear & Start Mode Entered by TI00n Pin Valid Edge Input (CR00n: Capture Register, CR01n: Capture Register) (3/3)

(c) TOC0n = 13H, PRM0n = 00H, CRC0n = 07H, TMC0n = 0AH



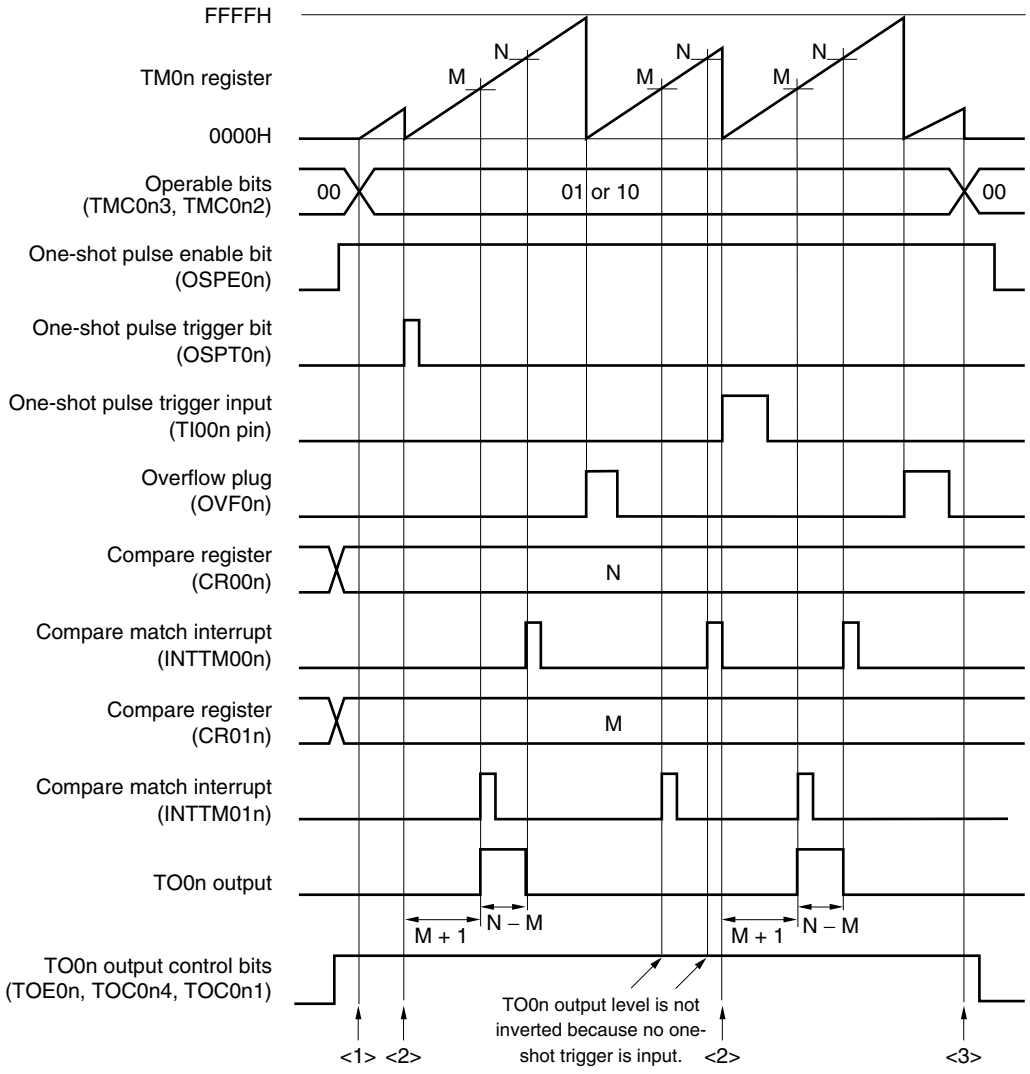
This is an application example where the pulse width of the signal input to the TI00n pin is measured.
By setting CRC0n, the count value can be captured to CR00n in the phase reverse to the falling edge of the TI00n pin (i.e., rising edge) and to CR01n at the falling edge of the TI00n pin.
The high- and low-level widths of the input pulse can be calculated by the following expressions.

- High-level width = [CR01n value] – [CR00n value] × [Count clock cycle]
- Low-level width = [CR00n value] × [Count clock cycle]

If the reverse phase of the TI00n pin is selected as a trigger to capture the count value to CR00n, the INTTM00n signal is not generated. Read the values of CR00n and CR01n to measure the pulse width immediately after the INTTM01n signal is generated.
However, if the valid edge specified by bits 6 and 5 (ES1n1 and ES1n0) of prescaler mode register 0n (PRM0n) is input to the TI01n pin, the count value is not captured but the INTTM00n signal is generated. To measure the pulse width of the TI00n pin, mask the INTTM00n signal when it is not used.

Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products
n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

Figure 7-50. Example of Software Processing for One-Shot Pulse Output Operation (1/2)



- Time from when the one-shot pulse trigger is input until the one-shot pulse is output
  = (M + 1) × Count clock cycle
- One-shot pulse output active level width
  = (N − M) × Count clock cycle

Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2,] 78K0/KD2 products

n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

(1) Receive buffer register 0 (RXB0)

This 8-bit register stores parallel data converted by receive shift register 0 (RXS0).

Each time 1 byte of data has been received, new receive data is transferred to this register from receive shift register 0 (RXS0).

If the data length is set to 7 bits the receive data is transferred to bits 0 to 6 of RXB0 and the MSB of RXB0 is always 0.

If an overrun error (OVE0) occurs, the receive data is not transferred to RXB0.

RXB0 can be read by an 8-bit memory manipulation instruction. No data can be written to this register.

Reset signal generation and POWER0 = 0 set this register to FFH.

(2) Receive shift register 0 (RXS0)

This register converts the serial data input to the RxD0 pin into parallel data.

RXS0 cannot be directly manipulated by a program.

(3) Transmit shift register 0 (TXS0)

This register is used to set transmit data. Transmission is started when data is written to TXS0, and serial data is transmitted from the TxD0 pins.

TXS0 can be written by an 8-bit memory manipulation instruction. This register cannot be read.

Reset signal generation, POWER0 = 0, and TXE0 = 0 set this register to FFH.

Cautions 1. Set transmit data to TXS0 at least one base clock (f_{XCLK0}) after setting TXE0 = 1.

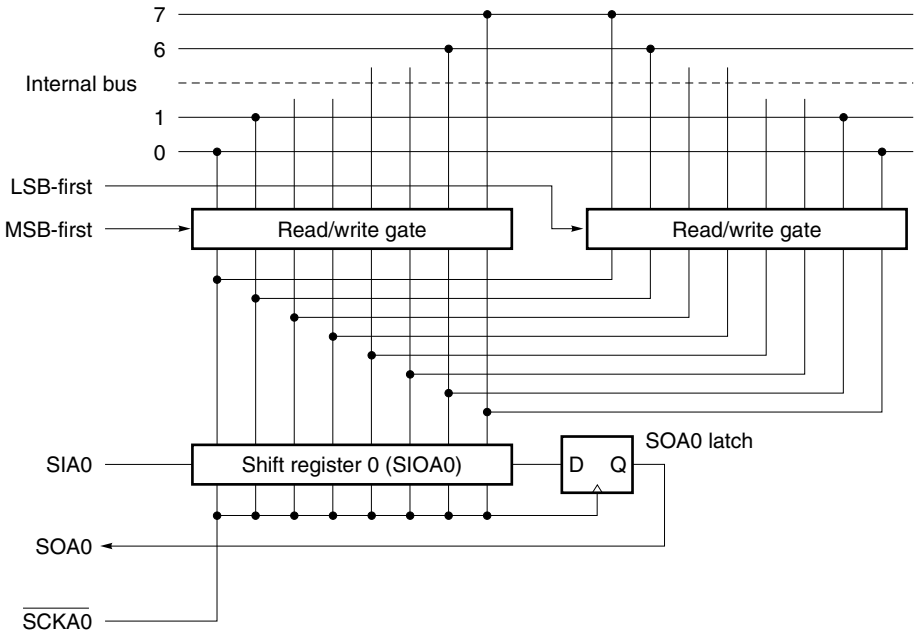
2. Do not write the next transmit data to TXS0 before the transmission completion interrupt signal (INTST0) is generated.

(c) Switching MSB/LSB as start bit

Figure 17-12 shows the configuration of serial I/O shift register 0 (SIOA0) and the internal bus. As shown in the figure, MSB/LSB can be read/written in reverse form.

Switching MSB/LSB as the start bit can be specified using bit 1 (DIR0) of serial operation mode specification register 0 (CSIMA0).

Figure 17-12. Transfer Bit Order Switching Circuit



Start bit switching is realized by switching the bit order for data written to SIOA0. The SIOA0 shift order remains unchanged.

Thus, switching between MSB-first and LSB-first must be performed before writing data to the shift register.

(d) Communication start

Serial communication is started by setting communication data to serial I/O shift register 0 (SIOA0) when the following two conditions are satisfied.

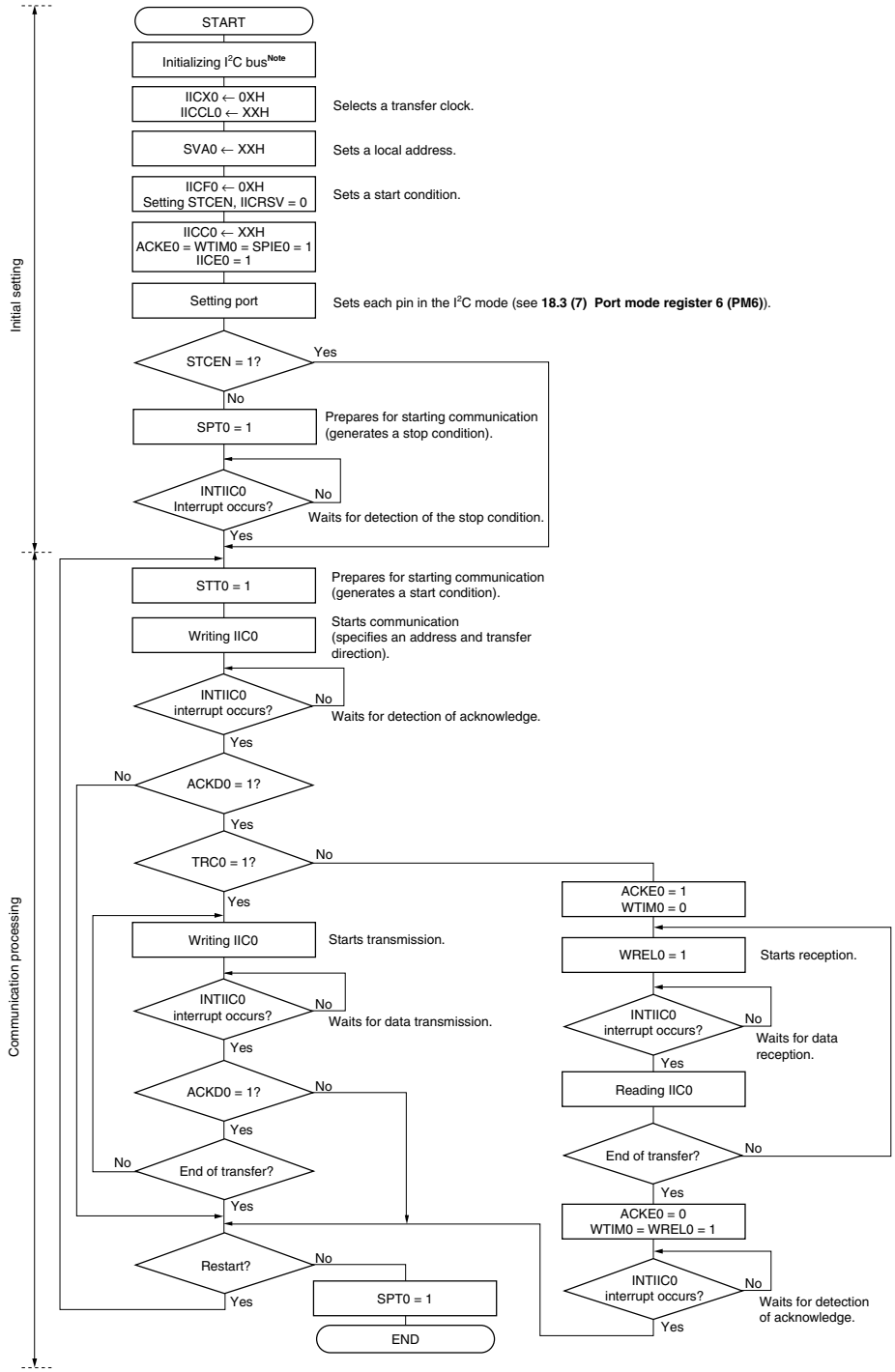
- Serial interface CSIA0 operation control bit (CSIAE0) = 1
- Serial communication is not in progress

Caution If CSIAE0 is set to 1 after data is written to SIOA0, communication does not start.

Upon termination of 8-bit communication, serial communication automatically stops and the interrupt request flag (ACSIIF) is set.

(1) Master operation in single-master system

Figure 18-23. Master Operation in Single-Master System



Note Release (SCL0 and SDA0 pins = high level) the I^2C bus in conformance with the specifications of the product that is communicating. If EEPROM is outputting a low level to the SDA0 pin, for example, set the SCL0 pin in the output port mode, and output a clock pulse from the output port until the SDA0 pin is constantly at high level.

Remark Conform to the specifications of the product that is communicating, with respect to the transmission and reception formats.

Table 20-2. Flags Corresponding to Interrupt Request Sources (2/2)

KB2	KC2	KD2	KE2	KF2	Interrupt Source	Interrupt Request Flag	Register	Interrupt Mask Flag	Register	Priority Specification Flag	Register
√	√	√	√	√	INTAD	ADIF	IF1L	ADMK	MK1L	ADPR	PR1L
√	√	√	√	√	INTSR0	SRIF0		SRMK0		SRPR0	
–	√	√	√	√	INTWTI	WTIIF		WTIMK		WTIPR	
√	√	√	√	√	INTTM51 Note 4	TMIF51		TMMK51		TMPR51	
–	√	√	√	√	INTKR	KRIF		KRMK		KRPR	
–	√	√	√	√	INTWT	WTIF		WTMK		WTPR	
–	√ Note 1	√	√	√	INTP6	PIF6		PMK6		PPR6	
–	√	√	√	√	INTP7	PIF7		PMK7		PPR7	
√ Note 2	√ Note 2	√ Note 2	√ Note 2	√	INTIIC0 Note 5	IICIF0 Note 6	IF1H	IICMK0 Note 7	MK1H	IICPR0 Note 8	PR1H
					INTDMU Note 5	DMUIF Note 6		DMUMK Note 7		DMUPR Note 8	
–	–	–	√ Note 3	√	INTCSI11	CSIIF11		CSIMK11		CSIPR11	
–	–	–	√ Note 3	√	INTTM001	TMIF001		TMMK001		TMPR001	
–	–	–	√ Note 3	√	INTTM011	TMIF011		TMMK011		TMPR011	
–	–	–	–	√	INTACSI	ACSIIF		ACSIMK		ACSIPR	

Notes 1. 48-pin products only.

2. INTIIC0: products whose flash memory is less than 32 KB
INTIIC0/INTDMU: products whose flash memory is at least 48 KB

3. Products whose flash memory is at least 48 KB only.

4. When 8-bit timer/event counter 51 is used in the carrier generator mode, an interrupt is generated upon the timing when the INTTM5H1 signal is generated (see **Figure 9-13 Transfer Timing**).

5. Do not use serial interface IIC0 and multiplier/divider simultaneously, because the flags corresponding to the interrupt request sources of serial interface IIC0 and multiplier/divider support both of these interrupt request sources. If software which operates serial interface IIC0 is developed by CC78K0 which is C compiler, do not select the check box of “Using Multiplier/Divider” on GUI of PM+.

6. If either interrupt source INTIIC0 or INTDMU is generated, bit 0 of IF1H is set (1).

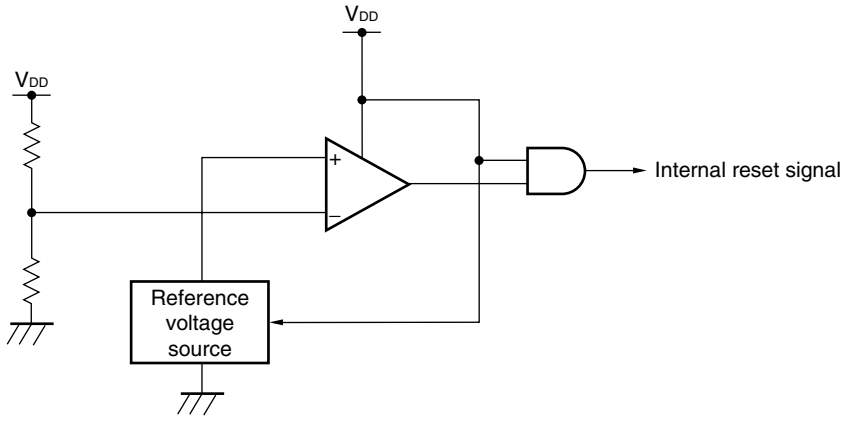
7. Bit 0 of MK1H supports both interrupt sources INTIIC0 and INTDMU.

8. Bit 0 of PR1H supports both interrupt sources INTIIC0 and INTDMU.

24.2 Configuration of Power-on-Clear Circuit

The block diagram of the power-on-clear circuit is shown in Figure 24-1.

Figure 24-1. Block Diagram of Power-on-Clear Circuit



24.3 Operation of Power-on-Clear Circuit

(1) In 1.59 V POC mode (option byte: POCMODE = 0)

- An internal reset signal is generated on power application. When the supply voltage (V_{DD}) exceeds the detection voltage (V_{POC} = 1.59 V ±0.15 V), the reset status is released.
- The supply voltage (V_{DD}) and detection voltage (V_{POC} = 1.59 V ±0.15 V) are compared. When $V_{DD} < V_{POC}$, the internal reset signal is generated. It is released when $V_{DD} \geq V_{POC}$.

(2) In 2.7 V/1.59 V POC mode (option byte: POCMODE = 1)

- An internal reset signal is generated on power application. When the supply voltage (V_{DD}) exceeds the detection voltage (V_{DDPOC} = 2.7 V ±0.2 V), the reset status is released.
- The supply voltage (V_{DD}) and detection voltage (V_{POC} = 1.59 V ±0.15 V) are compared. When $V_{DD} < V_{POC}$, the internal reset signal is generated. It is released when $V_{DD} \geq V_{DDPOC}$.

The timing of generation of the internal reset signal by the power-on-clear circuit and low-voltage detector is shown below.

27.9 Processing Time for Each Command When PG-FP4 or PG-FP5 Is Used (Reference)

The following table shows the processing time for each command (reference) when the PG-FP4 or PG-FP5 is used as a dedicated flash memory programmer.

Table 27-12. Processing Time for Each Command When PG-FP4 or PG-FP5 Is Used (Reference) (1/2)

(1) Products with internal ROMs of the 32 KB

Command of PG-FP4	Port: CSI-Internal-OSC (Internal high-speed oscillation clock (f_{RH})), Speed: 2.5 MHz	Port: UART-Ext-FP4CK (External main system clock (f_{EXCLK})), Speed: 115,200 bps	
		Frequency: 2.0 MHz	Frequency: 20 MHz
Signature	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)
Blankcheck	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)
Erase	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)
Program	2.5 s (TYP.)	5 s (TYP.)	5 s (TYP.)
Verify	1.5 s (TYP.)	4 s (TYP.)	3.5 s (TYP.)
E.P.V	3.5 s (TYP.)	6 s (TYP.)	6 s (TYP.)
Checksum	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)
Security	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)

(2) Products with internal ROMs of the 60 KB

Command of PG-FP4	Port: CSI-Internal-OSC (Internal high-speed oscillation clock (f_{RH})), Speed: 2.5 MHz	Port: UART-Ext-FP4CK (External main system clock (f_{EXCLK})), Speed: 115,200 bps	
		Frequency: 2.0 MHz	Frequency: 20 MHz
Signature	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)
Blankcheck	1 s (TYP.)	1 s (TYP.)	1 s (TYP.)
Erase	1 s (TYP.)	1 s (TYP.)	1 s (TYP.)
Program	5 s (TYP.)	9 s (TYP.)	9 s (TYP.)
Verify	2 s (TYP.)	6.5 s (TYP.)	6.5 s (TYP.)
E.P.V	6 s (TYP.)	10.5 s (TYP.)	10.5 s (TYP.)
Checksum	0.5 s (TYP.)	1 s (TYP.)	1 s (TYP.)
Security	0.5 s (TYP.)	0.5 s (TYP.)	0.5 s (TYP.)

Caution When executing boot swapping, do not use the E.P.V. command with the dedicated flash memory programmer.

29.1.2 Description of operation column

A: A register; 8-bit accumulator
X: X register
B: B register
C: C register
D: D register
E: E register
H: H register
L: L register
AX: AX register pair; 16-bit accumulator
BC: BC register pair
DE: DE register pair
HL: HL register pair
PC: Program counter
SP: Stack pointer
PSW: Program status word
CY: Carry flag
AC: Auxiliary carry flag
Z: Zero flag
RBS: Register bank select flag
IE: Interrupt request enable flag
( ): Memory contents indicated by address or register contents in parentheses
X_H, X_L: Higher 8 bits and lower 8 bits of 16-bit register
$\wedge$: Logical product (AND)
$\vee$: Logical sum (OR)
$\veebar$: Exclusive logical sum (exclusive OR)
$\overline{\ \ }$: Inverted data
addr16: 16-bit immediate data or label
jdisp8: Signed 8-bit data (displacement value)

29.1.3 Description of flag operation column

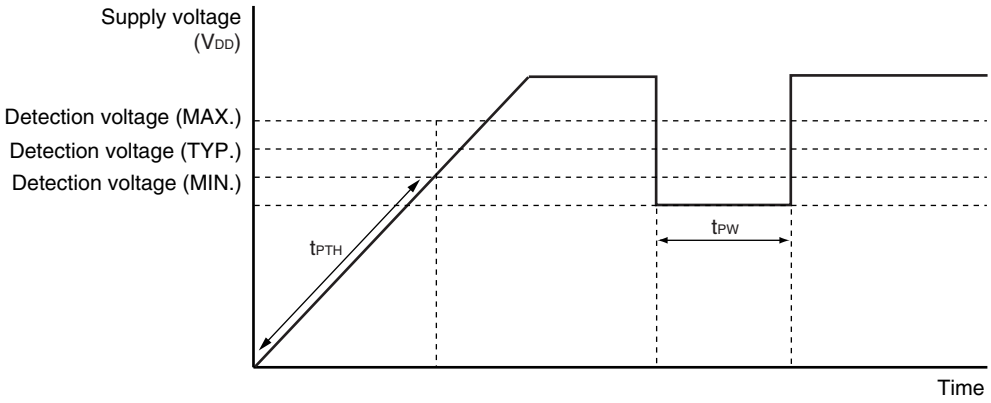
(Blank): Not affected
0: Cleared to 0
1: Set to 1
×: Set/cleared according to the result
R: Previously saved value is restored

Caution The pins mounted depend on the product. Refer to Caution 2 at the beginning of this chapter.

1.59 V POC Circuit Characteristics (T_A = –40 to +85°C, V_{SS} = EV_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POC}		1.44	1.59	1.74	V
Power supply voltage rise inclination	t_{PTH}	V_{DD}: 0 V → change inclination of V_{POC}	0.5			V/ms
Minimum pulse width	t_{PW}		200			μs

1.59 V POC Circuit Timing

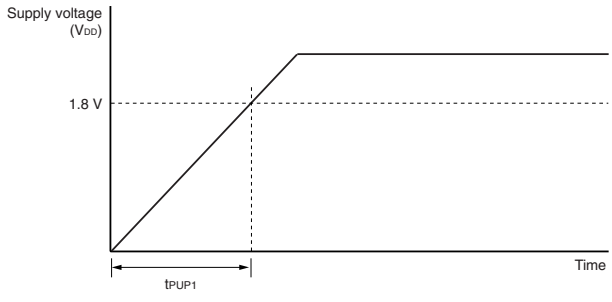


Supply Voltage Rise Time (T_A = –40 to +85°C, V_{SS} = EV_{SS} = 0 V)

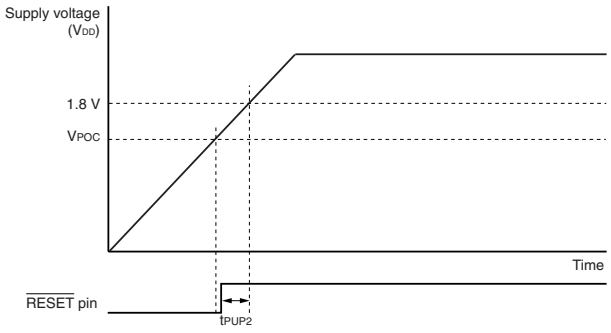
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Maximum time to rise to 1.8 V (V_{DD} (MIN.)) (V_{DD}: 0 V → 1.8 V)	t_{PUP1}	POCMODE (option byte) = 0, when $\overline{\text{RESET}}$ input is not used			3.6	ms
Maximum time to rise to 1.8 V (V_{DD} (MIN.)) (releasing $\overline{\text{RESET}}$ input → V_{DD}: 1.8 V)	t_{PUP2}	POCMODE (option byte) = 0, when $\overline{\text{RESET}}$ input is used			1.9	ms

Supply Voltage Rise Time Timing

• When $\overline{\text{RESET}}$ pin input is not used



• When $\overline{\text{RESET}}$ pin input is used



Caution The pins mounted depend on the product. Refer to Caution at the beginning of this chapter.

DC Characteristics (3/4)

(T_A = –40 to +110°C, 2.7 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, AV_{REF} ≤ V_{DD}, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Output voltage, low	V_{OL1}	P00 to P06, P10 to P17, P30 to P33, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P120, P130, P140 to P145	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 5.0 mA				0.7	V
			2.7 V ≤ V_{DD} < 4.0 V, I_{OL1} = 3.0 mA				0.7	V
	V_{OL2}	P20 to P27	AV_{REF} = V_{DD}, I_{OL2} = 0.4 mA				0.4	V
		P121 to P124	I_{OL2} = 0.4 mA				0.4	V
	V_{OL3}	P60 to P63	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 10.0 mA				2.0	V
			4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 3.0 mA				0.4	V
			2.7 V ≤ V_{DD} < 4.0 V, I_{OL1} =3.0 mA				0.6	V
Input leakage current, high	I_{LIH1}	P00 to P06, P10 to P17, P30 to P33, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P120, P140 to P145, FLMD0, $\overline{\text{RESET}}$	V_I = V_{DD}				3	μA
	I_{LIH2}	P20 to P27	V_I = AV_{REF} = V_{DD}				3	μA
	I_{LIH3}	P121 to 124 (X1, X2, XT1, XT2)	V_I = V_{DD}	I/O port mode			3	μA
				OSC mode			20	μA
Input leakage current, low	I_{LIL1}	P00 to P06, P10 to P17, P30 to P33, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P120, P140 to P145, FLMD0, $\overline{\text{RESET}}$	V_I = V_{SS}				–3	μA
	I_{LIL2}	P20 to P27	V_I = V_{SS}, AV_{REF} = V_{DD}				–3	μA
	I_{LIL3}	P121 to 124 (X1, X2, XT1, XT2)	V_I = V_{SS}	I/O port mode			–3	μA
				OSC mode			–20	μA
Pull-up resistor	R_U	V_I = V_{SS}			10	20	100	kΩ
FLMD0 supply voltage	V_{IL}	In normal operation mode			0		0.2V_{DD}	V
	V_{IH}	In self-programming mode			0.8V_{DD}		V_{DD}	V

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

Caution The pins mounted depend on the product. Refer to Caution at the beginning of this chapter.

(f) CSIA0 (master mode, $\overline{SCKA0}$…internal clock output)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
$\overline{SCKA0}$ cycle time	t_{KCY3}	4.0 V ≤ V_{DD} ≤ 5.5 V		600			ns
		2.7 V ≤ V_{DD} < 4.0 V		1200			ns
$\overline{SCKA0}$ high-/low-level width	t_{KH3}, t_{KL3}	4.0 V ≤ V_{DD} ≤ 5.5 V		$t_{KCY3}/2$ – 50			ns
		2.7 V ≤ V_{DD} < 4.0 V		$t_{KCY3}/2$ – 100			ns
SIA0 setup time (to $\overline{SCKA0}$↑)	t_{SIK3}			100			ns
SIA0 hold time (from $\overline{SCKA0}$↑)	t_{KSI3}			300			ns
Delay time from $\overline{SCKA0}$↓ to SOA0 output	t_{KSO3}	C = 100 pF[Note]	4.0 V ≤ V_{DD} ≤ 5.5 V			200	ns
			2.7 V ≤ V_{DD} < 4.0 V			300	ns
Time from $\overline{SCKA0}$↑ to STB0↑	t_{SBD}			$t_{KCY3}/2$ – 100			ns
Strobe signal high-level width	t_{SBW}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY3} – 30			ns
		2.7 V ≤ V_{DD} < 4.0 V		t_{KCY3} – 60			ns
Busy signal setup time (to busy signal detection timing)	t_{BYS}			100			ns
Busy signal hold time (from busy signal detection timing)	t_{BYH}			100			ns
Time from busy inactive to $\overline{SCKA0}$↓	t_{SPS}	4.0 V ≤ V_{DD} ≤ 5.5 V				$2t_{KCY3}$ + 100	ns
		2.7 V ≤ V_{DD} < 4.0 V				$2t_{KCY3}$ – 150	ns

Note C is the load capacitance of the $\overline{SCKA0}$ and SOA0 output lines.